

L Number	Hits	Search Text	DB	Time stamp
-	10	((int rlev l r int r-l vel or interlay r r inter-layer) adj insulating adj film) same (cu or copper) same damascene sam (diffusion near (preventive or preventing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:21
-	7	((interlevel or inter-level or interlayer or inter-layer) near insulating near film).ti,ab,clm. and (cu or copper).ti,ab,clm. and damascene and (diffusion near3 (preventive or preventing) near3 layer).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:24
-	50	((interlevel or inter-level or interlayer or inter-layer) near insulating near film) and (cu or copper) and damascene and (diffusion near3 (preventive or preventing) near3 layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:27
-	34	((interlevel or inter-level or interlayer or inter-layer) near insulating near film) and (cu or copper) and damascene and (diffusion near3 (preventive or preventing) near3 layer)) and (copper or cu).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:27
-	21	((interlevel or inter-level or interlayer or inter-layer) near insulating near film) and (cu or copper) and damascene and (diffusion near3 (preventive or preventing) near3 layer)) and (copper or cu).clm.) and (interlevel or interlayer or inter-leve or inter-layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:28
-	10	((interlevel or inter-level or interlayer or inter-layer) near insulating near film) and (cu or copper) and damascene and (diffusion near3 (preventive or preventing) near3 layer)) and (copper or cu).clm.) and (interlevel or interlayer or inter-leve or inter-layer).clm.) and (diffusion).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:29
-	9	((interlevel or interlayer or inter-level or inter-layer) same (copper or cu) same (metallization or interconnect or interconnection) same diffusion).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:31
-	6	((interlevel or interlayer or inter-level or inter-layer) same (copper or cu) same (metallization or interconnect or interconnection) same diffusion).clm.) and (diffusion near (prevent or preventing or prevented))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:32
-	9	((interlev l or interlayer or inter-level or inter-lay r) sam (copp r or cu) same (metallization r int rc nnect or int rc nnection) sam diffusion).clm.) and (m thod or process).clm.	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB	2003/06/29 17:36

-	2	(((interlevel r interlayer or inter-level r int r-layer) same (copper or cu) same (metallization or interconnect or int rconn ction) same diffusion).clm.) and (meth d or process).clm.) and damascene.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:32
-	1	((diffusion near preventive near insulating near layer) same (copper or cu)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:34
-	1	((diffusion near (preventing or preventive) near insulating near layer) same (copper or cu)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:34
-	5	((diffusion near2 (preventing or preventive) near2 insulating) same (copper or cu)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 17:35
-	17	((insulating or dielectric) adj film).clm. and (trench or via or opening).clm. and substrate.clm. and (barrier adj layer).clm. and ((diffusion or diffusing) adj barrier adj layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:11
-	4	((insulating or dielectric) adj film).clm. and (trench or via or opening).clm. and substrate.clm. and (barrier adj layer).clm. and ((diffusion or diffusing) adj barrier adj layer).clm. and (((insulating or dielectric) adj film) near5 substrate) and (((diffusion or diffusing) adj barrier adj layer) near5 ((insulating or dielectric) near film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:06
-	7	((insulating or dielectric) adj film).clm. and (trench or via or opening).clm. and substrate.clm. and (barrier adj layer).clm. and ((diffusion or diffusing) adj barrier adj layer).clm. and (((insulating or dielectric) adj film) near10 substrate) and (((diffusion or diffusing) adj barrier adj layer) near10 ((insulating or dielectric) near film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:07
-	11	((insulating or dielectric) adj film).clm. and (trench or via or opening).clm. and substrate.clm. and (barrier adj layer).clm. and ((diffusion or diffusing) adj barrier adj lay r).clm. and (((diffusion r diffusing) adj barrier adj layer) near10 ((insulating or dielectric) n ar film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:08

-	5	((insulating or dielectric) adj film).clm. and (trench or via or opening).clm. and substrate.clm. and (barrier adj layer).clm. and ((diffusion or diffusing) adj barrier adj layer).clm. and (((diffusion or diffusing) adj barrier adj layer) near10 ((insulating or dielectric) near film)) and (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:09
-	7	((insulating or dielectric) adj film).clm. and (trench or via or opening).clm. and substrate.clm. and (barrier adj layer).clm. and ((diffusion or diffusing) adj barrier adj layer).clm. and (copper or cu).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:09
-	11	((insulating or dielectric) adj film).clm. and (trench or via or opening).clm. and substrate.clm. and (barrier adj layer).clm. and ((diffusion or diffusing) adj barrier adj layer).clm. and (((insulating or dielectric) adj film) near5 substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:10
-	119	(interconnect or interconnection or metallization or wiring).clm. and substrate.clm. and (insulating or dielectric).clm. and (trench or via or opening).clm. and ((diffusion or diffusing) near barrier).clm. and (copper or cu).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:13
-	7	(interconnect or interconnection or metallization or wiring).clm. and substrate.clm. and (insulating or dielectric).clm. and (trench or via or opening).clm. and ((first or second or upper or lower or top or bottom) near (diffusion or diffusing) near barrier).clm. and (copper or cu).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:15
-	4	(interconnect or interconnection or metallization or wiring).clm. and substrate.clm. and ((first or second or upper or lower or top or bottom) near (insulating or dielectric)).clm. and (trench or via or opening).clm. and ((first or second or upper or lower or top or bottom) near (diffusion or diffusing) near barrier).clm. and (copper or cu).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:14
-	6	((first or second or upper or lower or top or bottom) near (interconnect or interconnection or metallization or wiring)).clm. and substrate.clm. and (insulating or dielectric).clm. and (trench or via or opening).clm. and ((first or second or upper or lower or top or bottom) near (diffusion or diffusing) near barrier).clm. and (copper or cu).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:16

-	93	((first or second or upper or lower or top or bottom) near (insulating or dielectric)) and ((first or second or upper or lower or top or bottom) near (interconnect or interconnection or metallization or wiring)) and ((first or second or upper or lower or top or bottom) near ((diffusion or diffusing) near barrier))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:24
-	11	((first or second or upper or lower or top or bottom) near (insulating or dielectric)).clm. and ((first or second or upper or lower or top or bottom) near (interconnect or interconnection or metallization or wiring)).clm. and ((first or second or upper or lower or top or bottom) near ((diffusion or diffusing) near barrier)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:25
-	9	((first or second or upper or lower or top or bottom) near (insulating or dielectric)).clm. and ((first or second or upper or lower or top or bottom) near (interconnect or interconnection or metallization or wiring)).clm. and ((first or second or upper or lower or top or bottom) near ((diffusion or diffusing) near barrier)).clm. and (trench or via or opening).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:25
-	7	((first or second or upper or lower or top or bottom) near (insulating or dielectric)).clm. and ((first or second or upper or lower or top or bottom) near (interconnect or interconnection or metallization or wiring)).clm. and ((first or second or upper or lower or top or bottom) near ((diffusion or diffusing) near barrier)).clm. and (trench or via or opening).clm. and (copper or cu).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:26
-	1	((first or second or upper or lower or top or bottom) near (insulating or dielectric)).clm. same ((first or second or upper or lower or top or bottom) near (interconnect or interconnection or metallization or wiring)).clm. same ((first or second or upper or lower or top or bottom) near ((diffusion or diffusing) near barrier)).clm. same (trench or via or opening).clm. same (copper or cu).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:27

-	4	((first or second or upper or lower or top or bottom) near (insulating or dielectric)) same ((first or second or upper or lower or top or bottom) near (interconnection or metallization or wiring)) same ((first or second or upper or lower or top or bottom) near ((diffusion or diffusing) near barrier)) same (trench or via or opening) same (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/18 14:31
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